

### **FEATURES**

- Average Forward Current:I<sub>F(AV)</sub>=2A
- Polarity: Color band denotes cathode



# **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)				
RS2AF-RS2MF	SMAF	RS2 <b>★</b> F	3000				



★:From A-M

### MAXIMUM RATINGS (Ta=25 unless otherwise noted)

Item	Symbol	Unit	Test Conditions	RS2							
				AF	BF	DF	GF	JF	KF	MF	
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		50	100	200	400	600	800	1000	
Maximum RMS Voltage	V <sub>RMS</sub>	V		35	70	140	280	420	560	700	
Average Forward Current	I <sub>F(AV)</sub>	Α	60Hz Half-sine wave, Resistance load, Ta=90 ℃	2.0							
Surge(Non-repetitive)Forward Current	I <sub>FSM</sub>	Α	60Hz Half-sine wave , 1 cycle , Ta=25℃	60							
Operation Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	°C		-55 ~ <b>+</b> 150							

## ELECTRICAL CHARACTERISTICS (Ta=25 unless otherwise specified)

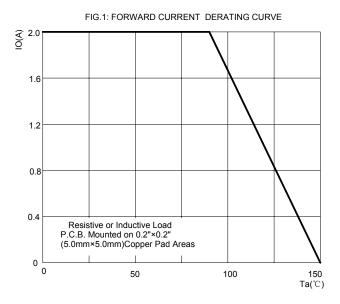
				RS2								
Item	Symbol	Unit	Test Condition		AF	BF	DF	GF	JF	KF	MF	
Peak Forward Voltage	$V_{F}$	V	I <sub>F</sub> =2.0A			1.3						
Maximum reverse recovery time	t <sub>rr</sub>	ns	I <sub>F</sub> =0.5A,I <sub>R</sub> =	1.0A,I <sub>rr</sub> =0.25A	150				250	500		
Peak Reverse Current	I <sub>RRM1</sub>	μА	V <sub>RM</sub> =V <sub>RRM</sub>	T <sub>a</sub> =25℃				5				
	I <sub>RRM2</sub>			T <sub>a</sub> =125℃	50							
Thermal	$R_{\theta J-A}$	°C/W	Between juncti	ion and ambient	55							
Resistance(Typical)	$R_{\theta J\text{-}L}$	CIVV	Between juncti	18								

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas



### **Typical Characteristics**



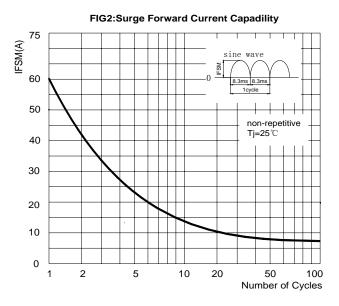


FIG.3: TYPICAL FORWARD CHARACTERISTICS

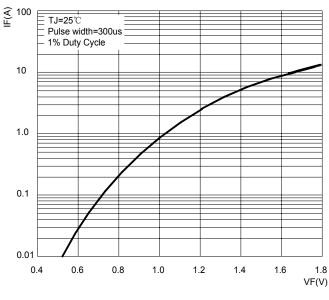


FIG.4: TYPICAL REVERSE CHARACTERISTICS

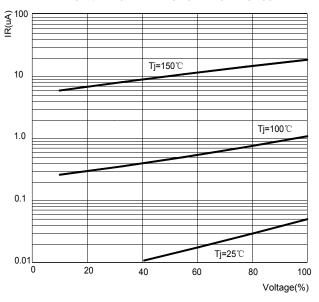
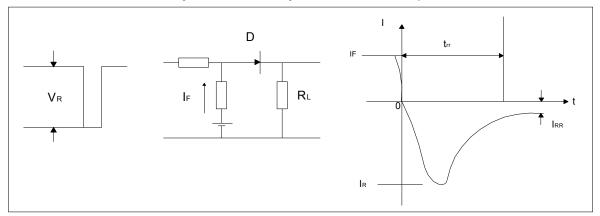
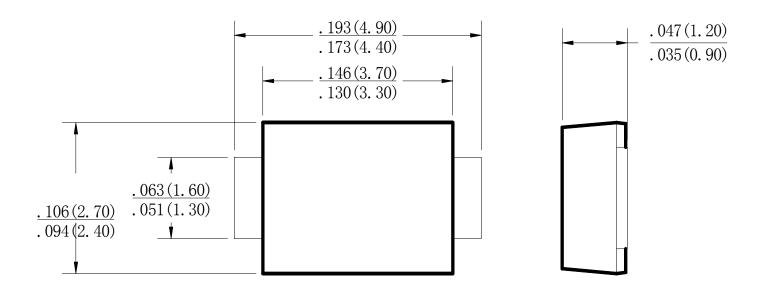


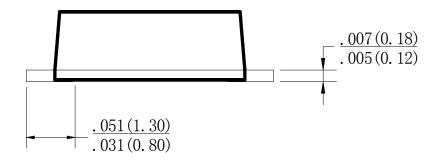
FIG.5: Diagram of circuit and Testing wave form of reverse recovery time





## **SMAF Package Outline Dimensions**





Dimensions in inches and (millimeters)



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